

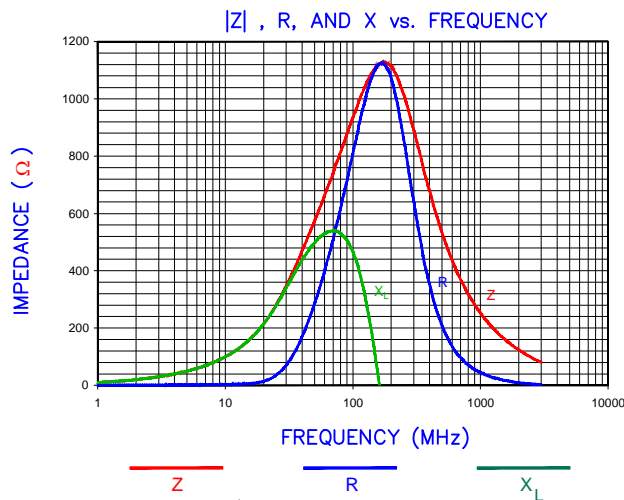
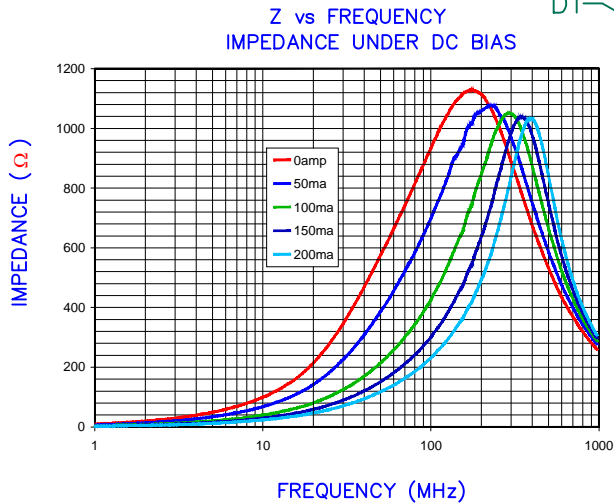
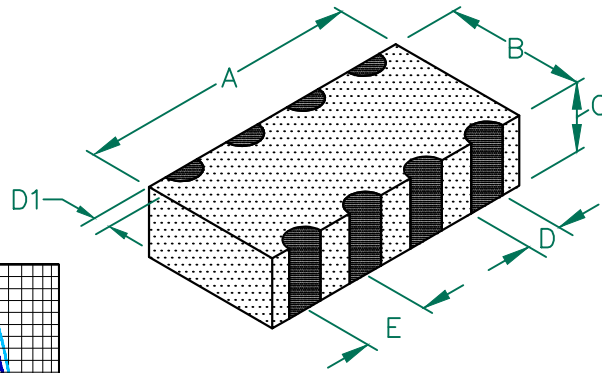
PHYSICAL DIMENSIONS:

A	3.20 [.126]	+ 0.20 [.008]
B	1.60 [.063]	+ 0.20 [.008]
C	0.80 [.031]	+ 0.20 [.008]
D	0.40 [.016]	+ 0.15 [.006]
D1	0.30 [.012]	+ 0.20 [.008]
E	0.80 [.031]	+ 0.10 [.004]

DA1206B102R-10

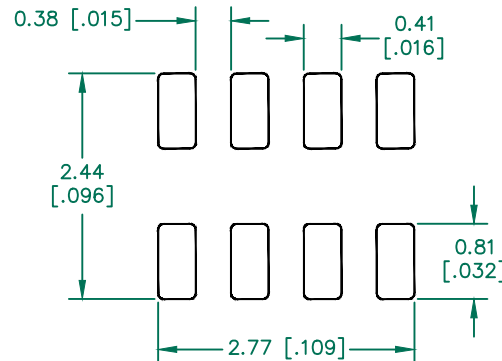
ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	1000	
Minimum	750	
Maximum	1250	0.8
LINE TO LINE INSULATION RESISTANCE >100 MΩ AT 75 VOLTS.		



AGILENT E4991A RF Impedance/Material Analyzer
HP 16194A Test Fixture. TEST REF. 3236

LAND PATTERNS FOR REFLOW SOLDERING

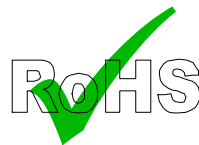
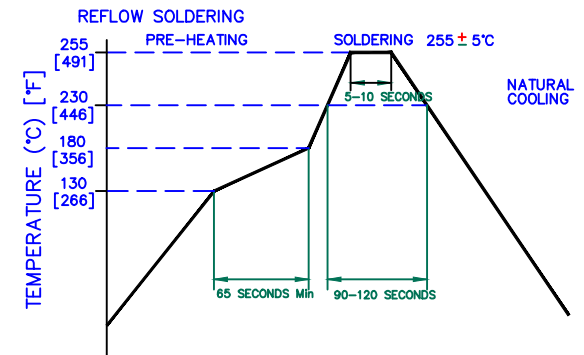


(For wave soldering, add 0.762 (0.030) to this dimension)

NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL.
2. TERMINATION FINISH IS 100% TIN.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. OPERATING TEMPERATURE TEMP: -40°C~+125°C. (INCLUDING SELF-HEATING)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird Tech, and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
F	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU				
E	CHANGE C DIMENSION	07/29/10	JUN				
D	UPDATE COMPANY LOGO	05/19/09	JRK				
C	D1 dim chgd from 0.008 ±0.004 to 0.012 ± 0.008. UPDATE COMPANY LOGO	10/30/07	JRK				
B	CHANGE C DIMS FROM .80 ADD RoHS	09/08/05	JRK				
A	ORIGINAL DRAFT	03/29/04	TMB	PROJECT/PART NUMBER:	REV	PART TYPE:	DRAWN BY:
REV	DESCRIPTION	DATE	INT	DA1206B102R-10	F	CO-FIRE	TMB
				DATE:	SCALE:	SHEET:	
				03/29/04	NTS		
				CAD #	TOOL #		
				DA1206B102R-10-F	-		1 of 1